



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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# PRINTED CIRCUIT BOARDS

01

4.11.2001

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 153 FR4 35 L20.35 P18\_10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

06\_153\_FR4\_35\_L20.35\_p18\_10

Layers	in $\mu$	Material	Build-Up	Assembly	
Layer-1	35 $\mu$	Copper		A1	
	100 $\mu$	Prepreg	(100 $\mu$ PrePreg-Type: 2125)		
	180 $\mu$	Prepreg	(180 $\mu$ PrePreg-Type: 7628)		
Layer-2	35 $\mu$	Copper			
	200 $\mu$	L-FR4			
Layer-3	35 $\mu$	Copper			A2
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
Layer-4	35 $\mu$	Copper			
	200 $\mu$	L-FR4			B
Layer-5	35 $\mu$	Copper			
	180 $\mu$	Prepreg			
	100 $\mu$	Prepreg		A1	
Layer-99	35 $\mu$	Copper			

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